

Technical Data :

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M 0 8 5 9 L C 1 6 0

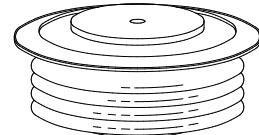
- Soft Recovery Rectifier
1600 V_{RRM};

HIGH POWER FAST RECOVERY RECTIFIER

Features:

- . All Diffused Structure
- . Fast Switching Performance
- . Blocking capability up to 1600 volts
- . Soft Reverse Recovery
- . Rugged Ceramic Hermetic Package
- . Pressure Assembled Device

CASE 3D



ELECTRICAL CHARACTERISTICS AND RATINGS

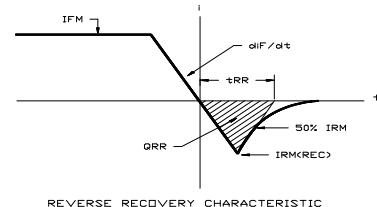
Reverse Blocking

Device Type	V _{RRM} (1)	V _{RSM} (1)
M0859LC	1600	1700

V_{RRM} = Repetitive peak reverse voltage

V_{RSM} = Non repetitive peak reverse voltage (2)

Repetitive peak reverse leakage	I _{RRM}	50 mA (3)
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REVERSE RECOVERY CHARACTERISTIC

Notes:

All ratings are specified for T_j=25 °C unless otherwise stated.

(1) All voltage ratings are specified for an applied

50Hz/60Hz sinusoidal waveform over the temperature range -40 to +150 °C.

(2) 10 msec. max. pulse width

(3) Maximum value for T_j = 150 °C.

(4) See parameter definition below :

Conducting - on state

Parameter	Symbol	Min.	Max.	Typ	Units	Conditions
Average value of on-state current	I _{F(AV)}		859		A	Sinewave, 180° conduction, T _s = 55°C
RMS value of on-state current	I _{FRMS}		1740		A	Nominal value
Peak one cycle surge (non repetitive) current	I _{FSM}		11000		A	10.0 msec (50Hz), sinusoidal wave-shape, 180° conduction, T _j = 150 °C
I square t	I ² t		605000		A ² s	10.0 msec
Peak on-state voltage	V _{FM}		1.50		V	I _{FM} = 1200 A; Duty cycle ≤ 0.01%; T _j = 125 °C
Reverse Recovery Current (4)	I _{RM(REC)}		80		A	I _{FM} = 1000 A; dI _F /dt = 25 A/μs; T _{jmax}
Reverse Recovery Charge (4)	Q _{rr}	*	200	μC		I _{FM} = 1000 A; dI _F /dt = 25 A/μs; T _{jmax}
Reverse Recovery Time (4)	t _{rr}	*	3.0	μs		

* For guaranteed maximum values, contact factory

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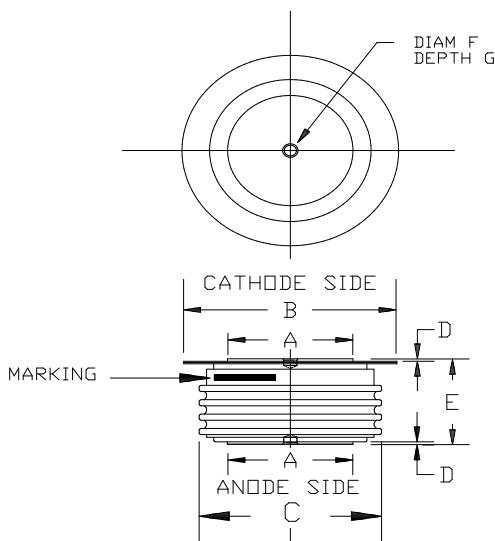
THERMAL AND MECHANICAL CHARACTERISTICS Rectifier

M0859LC160- Soft Recovery

Parameter	Symb ol	Min.	Max.	Typ.	Units	Conditions
Operating temperature	T _j	-40	+150		°C	
Storage temperature	T _{stg}	-40	+150		°C	
Thermal resistance - junction to case	R _{θ(j-c)}		0.043 0.086		°C/W	Double sided cooled Single sided cooled
Thermal resistance - case to sink	R _{θ(c-s)}		.015 .030		°C/W	Double sided cooled * Single sided cooled *
Mounting force	P	10.5	19.9		kN	
Weight	W			340	g	

* Mounting surfaces smooth, flat and greased

CASE OUTLINE AND DIMENSIONS



OUTLINE DIMENSIONS - CASE 3D				
DIMENSIONS	Min. mm	Max. mm	Min. In.	Max. In.
DIAM A	33.02	34.29	1.30	1.35
DIAM B	55.88	63.50	2.20	2.50
DIAM C	--	54.61	--	2.15
D	0.76	--	0.03	--
E	25.40	27.18	1.00	1.07
F	3.30	3.81	0.13	0.15
G	1.78	2.03	0.07	0.08

STRIKE DISTANCE = .73 INCH / 18.5 MM MIN.
CREEPAGE DISTANCE = 1.17 INCH / 29.7 MM MIN.